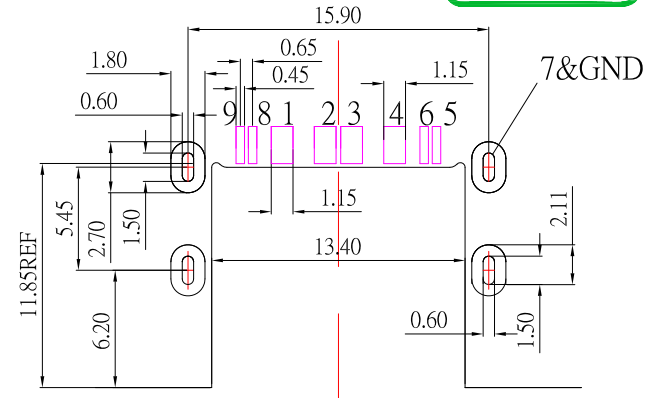




SUA-110E16-32x-S242

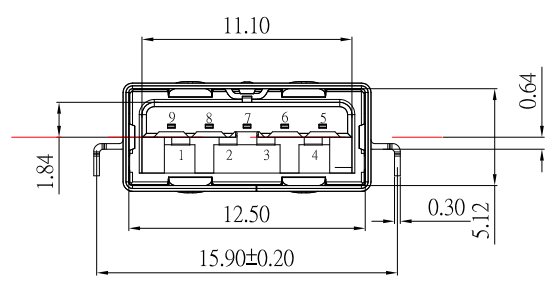
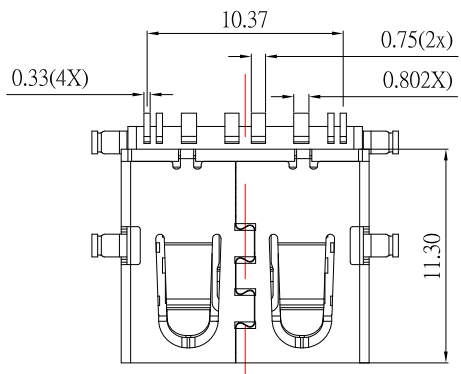
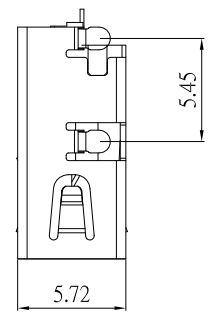
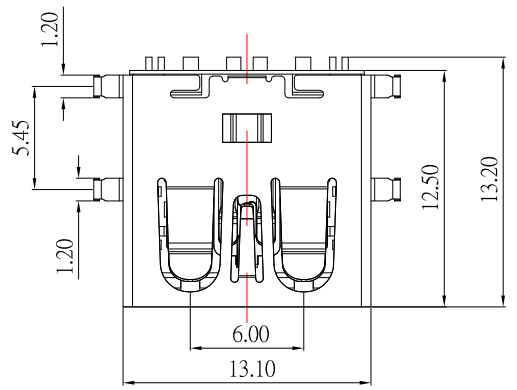
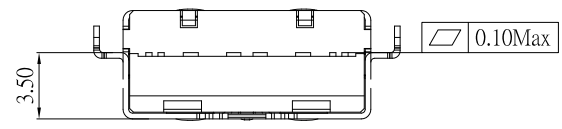
鍍層厚度：
Blank : 1u"
2 : 15u"
3 : 30u"



RECOMMENDED PCB LAYOUT

NOTE:

- 1.MATERIAL:
 - 1.1 Housing: LCP
 - 1.2 Contact: Phosphor Bronze
 - 1.3 Shell: SUS
- 2.Finish:
 - 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
 - 3.1 Rate: 3.0 A
 - 3.2 insulator Resistance:1000MΩ Min
 - 3.3 Dielectric Strength: 500V AC
 - 3.4 Contact Resistance: 30mΩ Max
 - 3.5 Operation Temperature: -25°C ~ +85°C
 - 3.6 Insertion Force: 35 N
 - 3.7 Extraction Force: 10 N



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	05/13/21			
CHECKED BY:	DATE	FINISH	MODLE	USB AF 3.0 沉板上H3.50mm 無捲邊 GEN 2
Jacky Chen	05/13/21			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110E16-32x-S242
Tony Kao	05/13/21	1 : 1	PART NO.	SUA-110E16-32x-S242
		SHEET NO.	1 of 1	
				SIZE A4
				VER R

ITEM NO.	DESCRIPTION	DRAWN	DATE